	OPERATING TEMPERATUR	RE RANGE	-40°C T0 + 85°C(NOTE			MPERATURE	-10°C T0 + 60°C	(NOTE 3))
	TEMPERATURE RANGE OPERATING HUMIDITY RANGE VOLTAGE CURRENT			STOF	AGE				
			40% T0 + 80% (NOTE				40% T0 + 70% (N		
			250V AC/DC				DF11-**DS-20	;(##)	
<u>/</u> 2			AWG24 : 2.5A AWG26 : 2.0A AWG28 : 1.0A	APPL	APPLICABLE CABLE		UL1061,1007 AWG24 TO 28		
				IFICATIO	ONS				
ТІ	ГЕМ		TEST METHOD			REC	QUIREMENTS	QT	A
	RUCTION								
GENERAL EX	AMINATION		AND BY MEASURING INSTRU	JMENT.	ACCOF	RDING TO DR	AWING.	Х	2
			ED VISUALLY.					Х	2
ELECTR	IC CHARA		DC OR 1000 Hz).		30mΩ	ΜΛΥ			—
	LOIDTANCE	TOOTIA (L	C OK 1000 HZ).		3011122			Х	-
MECHAN	VICAL CH	ARACTE	RISTICS						
MECHANICAL OPERATION		30 TIMES INSERTIONS AND EXTRACTIONS.			 CONTACT RESISTANCE: 30mΩ MAX. NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 			x	_
CONTACT INSERTION		□0.5±0.002 BY STEEL GAUGE.			-	INSERTION FORCE 4.4N MAX			
							E 0.3N MIN	X	-
VIBRATION		FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 2 h, FOR 3 DIRECTIONS.			② NO PAF	 NO ELECTRICAL DISCONTINUITY OF 1µs. NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 			-
SHOCK		490 m/s ² DURATION OF PULSE 11 ms AT 3 TIMES DIRECTIONS.			2 NO	 NO ELECTRICAL DISCONTINUITY OF 1μs. NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 			-
ENVIRO	NMENTAL	CHARA	ACTERISTICS						
RAPID CHANGE OF TEMPERATURE		TEMPERATURE -55 \rightarrow 5 TO 35 \rightarrow 85 \rightarrow 5 TO 35 °CTIME30 \rightarrow 10 TO 15 \rightarrow 30 \rightarrow 10 TO 15 minUNDER 5 CYCLES.			2 NO	 CONTACT RESISTANCE: 30mΩ MAX. NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 			-
DAMP HEAT (STEADY STATE)		EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.			 CONTACT RESISTANCE: 30mΩ MAX. NO DAMAGE, CRACK OR LOOSENESS OF 				
STEADY STA REMARKS NOTE 1:INCLU NOTE 2:NO C	UDING THE TEI	MPERATUR	E RISE BY CURRENT		1 CON 2 NO PAF	DAMAGE, CR RTS.	ACK OR LOOSENESS OF	x	
STEADY STA REMARKS NOTE 1:INCLI NOTE 2:NO C NOTE 3:APPL AFTE	UDING THE TEI CONDENSING. LY TO THE CON	MPERATURE IDITION OF I DN PCB, OPE	E RISE BY CURRENT LONG TERM STORAGE FOR L ERATION TEMPERATURE AND	JNUSED PRODU	1 COM 2 NO PAF	DAMAGE, CR RTS. DRE MOUNTI	ACK OR LOOSENESS OF	X	<u> </u>
STEADY STA REMARKS NOTE 1:INCLI NOTE 2:NO C NOTE 3:APPL AFTE STOP	UDING THE TEI ONDENSING. Y TO THE CON ER MOUNTED C RAGE DURING	MPERATURI IDITION OF I DN PCB, OPE TRANSPOR	E RISE BY CURRENT LONG TERM STORAGE FOR U ERATION TEMPERATURE AND TATION.	JNUSED PRODU D HUMIDITY RAN	1 CON 2 NO PAF	DAMAGE, CR RTS. DRE MOUNTI	ED ON PCB, ITERIM		
STEADY STA REMARKS NOTE 1:INCLI NOTE 2:NO C NOTE 3:APPL AFTE STOF	UDING THE TEH CONDENSING. Y TO THE CON ER MOUNTED C RAGE DURING	MPERATURI IDITION OF I DN PCB, OPE TRANSPOR	E RISE BY CURRENT LONG TERM STORAGE FOR L ERATION TEMPERATURE AND TATION.	JNUSED PRODU D HUMIDITY RAN	1 CON 2 NO PAF	DAMAGE, CF	CHECKED	DA 2018	3110
STEADY STA REMARKS NOTE 1:INCLI NOTE 2:NO C NOTE 3:APPL AFTE STOF	UDING THE TEH CONDENSING. Y TO THE CON ER MOUNTED C RAGE DURING	MPERATURI IDITION OF I DN PCB, OPE TRANSPOR	E RISE BY CURRENT LONG TERM STORAGE FOR U ERATION TEMPERATURE AND TATION.	JNUSED PRODU D HUMIDITY RAN	1 CON 2 NO PAF	DAMAGE, CF RTS. DRE MOUNTI PLIED FOR IN	ED ON PCB, ITERIM CHECKED SZ. ONO D KJ. KATAYOSE	DA 2018 2005	3110 5010
STEADY STA REMARKS NOTE 1:INCLI NOTE 2:NO C NOTE 3:APPL AFTE STOF	UDING THE TEH CONDENSING. Y TO THE CON ER MOUNTED C RAGE DURING	MPERATURI IDITION OF I DN PCB, OPE TRANSPOR	E RISE BY CURRENT LONG TERM STORAGE FOR L ERATION TEMPERATURE AND TATION.	JNUSED PRODU D HUMIDITY RAN	1 CON 2 NO PAF	DAMAGE, CF	ED ON PCB, ITERIM CHECKED SZ. 0N0 D KJ. KATAYOSE D TY. 0MA	DA 2018	B110 5010 5010
STEADY STA REMARKS IOTE 1:INCLI IOTE 2:NO C IOTE 3:APPL AFTE STOF STOF COUN 2 2	UDING THE TEH CONDENSING. Y TO THE CON ER MOUNTED C RAGE DURING	MPERATURI IDITION OF I DN PCB, OPE TRANSPOR	E RISE BY CURRENT LONG TERM STORAGE FOR L ERATION TEMPERATURE AND TATION.	JNUSED PRODU D HUMIDITY RAN	1 CON 2 NO PAF	DAMAGE, CF RTS. DRE MOUNTI PLIED FOR IN PLIED FOR IN APPROVE CHECKEI	ED ON PCB, ITERIM CHECKED SZ. 0N0 D KJ. KATAYOSE D TY. 0MA	DA 2018 2005 2005	3110 5010 5010 5010
STEADY STA REMARKS IOTE 1:INCLI IOTE 2:NO C IOTE 3:APPL AFTE STOF COUN 2 Jnless oth	UDING THE TEH CONDENSING. Y TO THE CON RAGE DURING	MPERATURE IDITION OF I DN PCB, OPE TRANSPOR TRANSPOR ESCRIPTIC DIS-I ccifid , ref	E RISE BY CURRENT LONG TERM STORAGE FOR L ERATION TEMPERATURE AND TATION.	JNUSED PRODU D HUMIDITY RAN DES TS. 1	1 CON 2 NO PAF	DAMAGE, CF RTS. DRE MOUNTI PLIED FOR IN APPROVE CHECKEI DESIGNE DRAWN	ED ON PCB, ITERIM CHECKED SZ. ONO D KJ. KATAYOSE D TY. OMA D IO. DENPOUYA	DA 2018 2005 2005 2005 2005	3110 5010 5010 5010 5010
STEADY STA REMARKS NOTE 1:INCLI NOTE 2:NO C NOTE 3:APPL AFTE STOP COUN 2 Unless oth	UDING THE TEH CONDENSING. Y TO THE CON ER MOUNTED C RAGE DURING	MPERATURE IDITION OF I DN PCB, OPE TRANSPOR TRANSPOR ESCRIPTIO DIS-I cifid , refe	E RISE BY CURRENT LONG TERM STORAGE FOR U ERATION TEMPERATURE AND TATION.	JNUSED PRODU D HUMIDITY RAN DES TS. 1	1 CON 2 NO PAF	DAMAGE, CF RTS. DRE MOUNTI PLIED FOR IN APPROVE CHECKEI DESIGNE DRAWN	ED ON PCB, ITERIM CHECKED SZ. ONO D KJ. KATAYOSE D TY. OMA D 10. DENPOUYA 10. DENPOUYA	DA 2018 2005 2005 2005 2005	3110 5010 5010 5010 5010